Pictures of the DATE 2013 Conference
2013-03-28

You will find more conference pictures in the DATE Gallery.

DATE Best Paper Awards
2013-03-19

The DATE 2012 best paper is:

**COMPOSITIONAL SYSTEM-LEVEL DESIGN EXPLORATION WITH PLANNING OF HIGH-LEVEL SYNTHESIS**
Hung-Yi Liu, Michele Petracca, and Luca P. Carloni, Columbia University, US.

The DATE 2013 best papers are:

**D Track**

**AVICA: AN ACCESS-TIME VARIATION-INSENSITIVE L1 CACHE ARCHITECTURE**
Seokin Hong and Soojea Kim - Korea Advanced Institute of Science and Technology, KR

**T Track**

**HANDLING DISCONTINUOUS EFFECTS IN MODELING SPATIAL CORRELATION OF WAFER-LEVEL ANALOG/RF TESTS**
Ke Huang and Yongsoo Malhi - University of Texas at Dallas, US

and

Nathan Kupp - Yale University, US

and

John Carulli - Texas Instruments, US

**E Track**

**FIFO CACHE ANALYSIS FOR WCET ESTIMATION: A QUANTITATIVE APPROACH**
Nan Guan, Xiping Yang and Wang Yi - Uppsala University, SE

and

Mingsong Lv - Northeastern University, CN

Congratulations to the winners!

First pictures of DATE 2013 Opening and Keynotes
2013-03-20

You will find more pictures in the DATE Gallery.

DATE 2014 in Dresden, Germany - Preliminary Call for Papers available
2013-03-19

DATE 2014 will take place again at the ICC in Dresden, Germany March 24-28, 2014. The preliminary Call for papers is now available for download [here](http://www.date-conference.com) (PDF, 144 kB).

The 2013 event highlights High-Performance Low-Power Computing and Electronic Technologies for Smart Cities.
Exhibition

The DATE Exhibition once again the premier European event for industrial professionals and academics alike. This exhibition will feature suppliers of development tools and platforms for hardware and software development, showing a range of products from the front-end to back-end chip design through to silicon test and manufacture, from system architecture through to embedded software implementation and networking. Grenoble’s leadership in microelectronics will be highlighted by Minalogic and Grenoble-Isère/AEPI with a cluster of 10 local leading companies.

The 2013 Exhibition will run for three days (Tuesday 19 – Thursday 21 inclusive) and take place on the ground floor, adjacent to the main entrance and registration desks.

Exhibitors’ profiles are available at:
http://www.date-conference.com/exhibitors-sponsors

Exhibition Theatre features Hot Topics, best practice and panels

As special feature for exhibition visitors offers three days of high-quality program free of charge in the Exhibition Theatre. Located in the midst of the exhibition area, the Exhibition Theatre program provides best practice on design for various fields of applications and a special selection of the conference program with special Hot Topics Tutorials and Panel sessions with industry leaders. At DATE 2013 the partnering regions of Silicon Saxony, DSP Valley, Minalogic and High Tech NL will present in the Exhibition Theatre their work and the goals they want to achieve. These four of the leading European micro- and nano-electronics regions recently began to join their research, development and production expertise to form the transnational, research-driven cluster Silicon Europe, actually one of the largest technology clusters of the world.

All sessions can be attended with a free-of-charge exhibition registration, a conference registration is not required.

Detailed information on the Exhibition Theatre sessions is available at:
http://www.date-conference.com/group/exhibition/exhibition-theatre

University Booth

Another hot-spot in the exhibition is the University Booth where the leading universities and research institutes will present their latest research results with hardware and software demonstrators.

With 11 sessions and 9 presentations running in parallel, the University Booth is a unique place showcasing a vast bunch of innovations covering EDA, design and test which will shape and revolutionize the way we design products in the future.

DATE 2013 will be at the Alpexpo Conference Center in Grenoble

Located in the heart of the Alps and surrounded by the outstanding natural beauty of the Belledonne, Chartreuse and Vercors massifs, Grenoble is the key semiconductor site in Europe with more than 38,000 people in micro- and nano-technologies (24000) and embedded software (14000). Grenoble provides the second largest research site in France with 15 research centres and universities. There are some 100 start-up companies located in the area in addition to 117 companies – 81% of which are SMEs. Minatec is a centre for innovation for micro- and nano-technology and contributes to the reputation of Grenoble as one of Europe’s key scientific centres. Alpexpo Conference Center is located in close proximity to central Grenoble and provides a modern, well-equipped location for DATE. It is one of Europe’s most prestigious venues for economic, cultural and sporting events.

Alpexpo is a 15-minute tram ride from the centre of Grenoble. Information on hotel bookings at:
http://www.date-conference.com/location

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Don’t miss the Special Day on “High-Performance, Low-Power Computing” on Wednesday (27)
2013-02-18

Don’t miss the Special Day on “Electronic Technologies for Smart Cities” on Thursday (29)
2013-02-18

DATE 2013 Announces Availability of the Advance Program (31)
2013-01-18

About 200 papers have been selected from over 1,000 submissions for regular presentations in 57 sessions, allowing top researchers from all over the world to present their most important and recent research findings in track D
DATE's technical session program will be supplemented by 15 Special Sessions including five Embedded Tutorials [1], seven Hot Topic Sessions [2] and three Panels [3].

Extra tracks will be dedicated to two Special Days:


Each special day will have a full program of keynotes, panels, tutorials and technical presentations.

From Tuesday to Thursday, about 100 Interactive Presentations organized into five IP Sessions in a face-to-face discussion area will contribute to scientific interactions on emerging and open problems on Design, Verification, and Test.

In addition, DATE 2013 will organize an Exhibition Theatre [6] program that will provide a mix of panel discussions and user presentations giving exhibition visitors and conference delegates a dynamic overview of key technical and business issues in electronic and embedded systems design.

To complement the regular conference program, the DATE Friday’s Workshops initiative [7] will offer workshops on current and emerging important issues in design, test, EDA, and software.

**Detailed Descriptions**

1. **Embedded Tutorials**
   - [ ] Reliability Analysis/Reloading: How Will We Survive?
   - [ ] On the Use of GPU-GPUs for Accelerating Computing Intensive EDA Applications
   - [ ] Advances in Asynchronous Logic: from Principles to GALS & NAC, Recent Industry Applications, and Commercial CAD Tools
   - [ ] From Multi-core SoC to Scale Out Processors
   - [ ] Closed-Loop Control for Power and Thermal Management in Multi-core Processors

2. **Hot Topic Sessions**
   - [ ] IP Subspaces: The Next Productivity Wave?
   - [ ] Design for Reliability, Manufacturability, Reliability, and Debug: Many Faces of the Same Coin?
   - [ ] Security Challenges in Automotive Hardware/Software Architecture Design
   - [ ] Emerging Nanoscale Devices: A Booster for High Performance Computing
   - [ ] Energy-Efficient Design and Test Techniques for Future Multi-Core Systems
   - [ ] Counterfeiting Counterfeits: Attacks on Micro-Electronics
   - [ ] Reliability Challenges of Real-time Systems in Forthcoming Technology Nodes

3. **Panels**
   - [ ] Will 3D IC Remain a Technology of the Future... Even in the Future?
   - [ ] Can Energy Harvesting Deliver Enough Power for Automotive Electronics?

4. **Special Day 1: High-Performance Low-Power Computing**
   
   This special day will feature four sessions covering System, IC Architecture, Many-Core SoC and Fabrication Technology Approaches for Energy-Efficiency. As precisely noted by the Special Day Chair, Dr. A. Jemya from CEA-Leti, “The environmental pressure is generating stringent constraints on computing systems where energy-efficiency needs to be improved by a factor 50 in the next five years. To reach this goal, system and architecture solutions need to be aligned with circuit and fabrication process solutions”. This event will be held on Wednesday, March 20.

5. **Special Day 2: Electronic Technologies for Smart Cities**
   
   This special day will provide a technical insight on several electronic technologies, which are at the basis of the Smart Cities of the future. “The smart city is a buzz-word in the last couple of years, especially in Europe, and significant investments have been made by public authorities, locally and internationally, to promote, define and implement the concept. A city can be made “smart” in several ways, most of which can be combined: mobility, health-care, energy efficiency, services to the citizens and so forth represent challenges that a smart-city must face”. “Electronic devices, circuits, systems and software constitute the enabling technologies for implementing the aforementioned applications”, states Prof. Enrico Macii from Politecnico di Torino, Chair of the Electronic Technologies for Smart Cities Special Day. This event will be held on Thursday, March 21.

6. **Exhibition Theatre**
   
   The Exhibition Theatre program will host a series of discussions to provide a broad view on the technical and business challenges in current and future design practices. Industrial testimonials will offer engineers an insight into good working practices and current design methods on topics like Power Integrity/Verification, Data Management and Memory Architectures in Many-core SoCs, and Optimization of Analog Designs. Also, the use of 3DIC technology today and in the future will be discussed by a panel in the Exhibition Theatre. Highlighting a major step in joining forces at European Level, the Silicon Europe initiative will present a panel session on the available competences in already existing clusters in Dresden, Eindhoven, Grenoble, and Leuven and will give an outlook on how they want to make a major step forward by close co-operation.

7. **Friday's Workshops**
   
   The Friday's Workshops program includes nine workshop themes, ranging from embedded systems to 3D integration. Three workshops focused on broad embedded systems field are: Embedded Parallel Computing Platforms Platform 2012/INFORM Embedded Many-Core Accelerations, and Reconfigurable Computing. One workshop is focused on methods for system-level design, in particular on the integration of SystemC Design and Verification with AMS and Algorithmic Design. 3D integration workshop, building on the success from the previous four years, covers a broad spectrum of topics from technology and test to chip package and board co-design challenges. Two workshops discuss the lessons learned from large multi-institutional research programs for attended/intended in the Reliability and Resilient Design Through Software Approaches. For the first time at DATE, the workshop entitled Neuroemotional and Brain-Based Computing Systems is proposed to discuss new emerging areas relevant to the electronic design automation community. Finally, a workshop focusing on Industry-Driven Approaches for Cost-effective Certification of Safety-Critical, Mixed-Criticality Systems (MICRIS) aims at gathering a strong industrial community to discuss and evaluate new Howany architectures, mechanisms and safety guidelines to achieve a more cost-effective, precise, and scalable certification.

For further information please visit the DATE Web site from January 2013

www.date-conference.com [32]

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DATE 2013 Preliminary Programme available [36]
2012-12-20

DATE 2013 attracts more than 1,000 submissions [37]
2012-10-22

Special Days at DATE 2013 will focus on two areas bringing new challenges to the system design community: High-Performance Low-Power Computing and Electronic Technologies for Smart Cities.

The Special Day on High-Performance Low-Power Computing is organized by Dr. Ahmed Jerraya from CEA-Leti and will take place on Wednesday, March 20th. It will feature four sessions covering System, IC Architecture, Many-Core SoC and Fabrication Technology Approaches for Energy Efficiency. A keynote on Energy-Efficient Computing will be delivered by Dr. John Goodacre from ARM.

The Special Day on Electronic Technologies for Smart Cities is organized by Prof. Enrico Macii from Politecnico di Torino, General Chair of DATE 2013 and will happen on Thursday, March 21st. The presentations grouped into four sessions will address the following themes: Smart Grid and Buildings, Smart Data Centres, Smart Health and Smart Mobility. The related keynote session will feature presentations by high-level politicians from EU countries and the European Commission, including Prof. Francesco Profumo, Italian Minister for Education, University and Research.

General Information on DATE 2013
In recent years, DATE travels up and down between the European semiconductor centres Dresden (2010+2012) and Grenoble (2011). DATE 2013 will take place again at Alpexpo in Grenoble, a key European semiconductor site with 38,000+ people in micro- and nano-technology and embedded software. It is the second largest research area in France, with many research laboratories reporting to the French National Council for Scientific Research (CNRS), University of Grenoble, and Centre for Atomic and Renewable Energies (CEA). There are some hundred start-up companies located in the area in addition to 117 companies - 81% of which are SMEs.

For further information please visit: www.date-conference.com [38].

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